

Abstract of the Invention

5 An improved cooling system provides cooling
away from the surface of electrical and electronic
components with very low parasitic power consumption
and very high heat transfer rates. The component to
be cooled is in thermal contact with a cold plate
evaporator device. Refrigerant is circulated by a
liquid refrigerant pump to the cold plate evaporator
10 device, and the liquid refrigerant is at least
partially evaporated by the heat generated by the
component. The vapor is condensed by a conventional
condenser coil and the condensed liquid along with
any unevaporated liquid is returned to the pump. The
15 system operates nearly isothermally in both
evaporation and condensation.